

Drop-in CIRCULATOR

Drop-in ISOLATOR

UMTS

LTE Band

PCB Soldering Re-flow

Compact Package Design for PCB Applications



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Drop-in Isolator

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Velký výběr
vysokofrekvenčních
konektorů naleznete
na našem webu
www.atd-elektronik.cz.

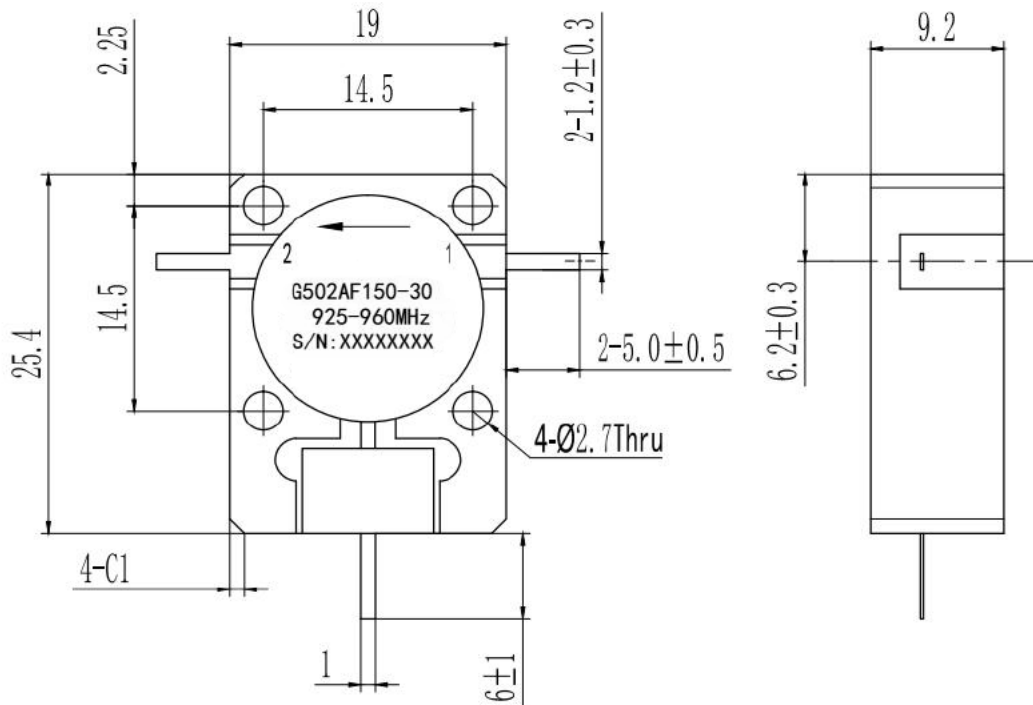


Drop-in Isolator G502A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimension



3.Specifications

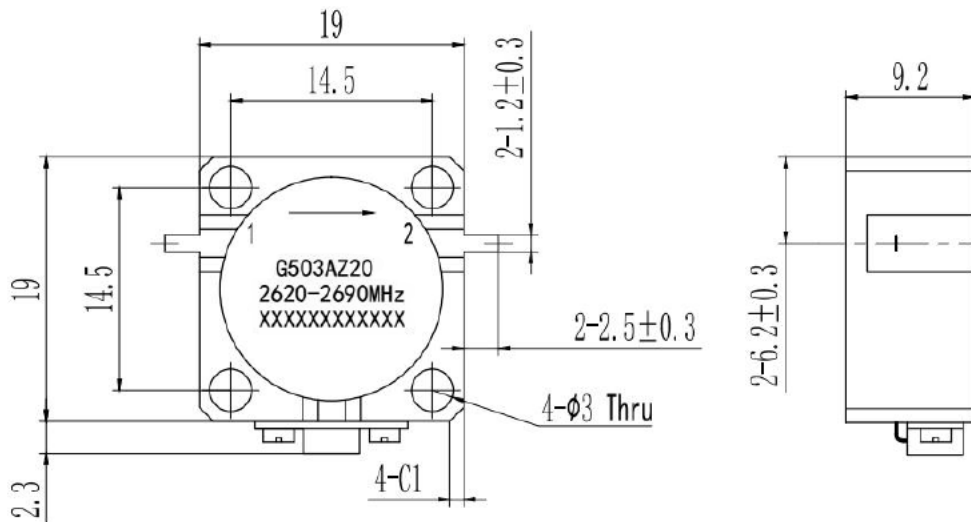
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G502A[925-960]MHz	0.925	0.960	0.943	0.035	22	0.3	1.17	150	
G502A[1600-1630]MHz	1.600	1.630	1.6150	0.030	23	0.25	1.15	150	
G502A[1689-1710]MHz	1.689	1.710	1.6995	0.021	23	0.2	1.15	150	
G502A[1800-2200]MHz	1.800	2.200	2.0000	0.400	22	0.3	1.2	100	
G502A[1805-1880]MHz	1.805	1.880	1.8375	0.075	23	0.25	1.17	150	
G502A[2000-2500]MHz	2.000	2.500	2.2500	0.500	18	0.4	1.3	150	
G502A[2100-2200]MHz	2.100	2.200	2.1500	0.100	22	0.3	1.2	150	
G502A[2300-2400]MHz	2.300	2.400	2.3500	0.100	22	0.25	1.17	150	-65
G502A[2555-2660]MHz	2.555	2.660	2.6075	0.105	22	0.25	1.17	150	-65
G502A[3100-3500]MHz	3.100	3.500	3.3000	0.400	20	0.35	1.2	100	
G502A[3400-4200]MHz	3.400	4.200	3.800	0.800	15	0.45	1.4	150	

Drop-in Isolator G503A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions



3.Specifications

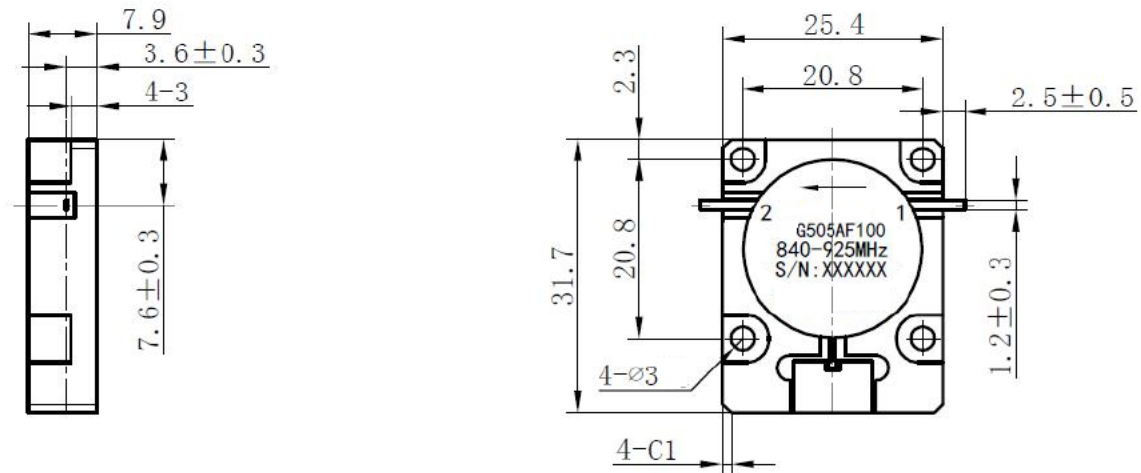
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G503A[925-960]MHz	0.925	0.960	0.943	0.035	22	0.3	1.17	60	
G503A[1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.17	60	
G503A[1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	60	
G503A[1880-1920]MHz	1.880	1.920	1.9000	0.040	25	0.25	1.15	100	
G503A[1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.17	60	
G503A[1930-1990]MHz	1.930	1.990	1.9600	0.060	23	0.25	1.17	60	
G503A[2010-2025]MHz	2.010	2.025	2.0170	0.015	25	0.25	1.17	60	
G503A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	60	
G503A[2620-2690]MHz	2.620	2.690	2.6550	0.070	23	0.25	1.17	60	

Drop-in Isolator G505A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions



3.Specifications

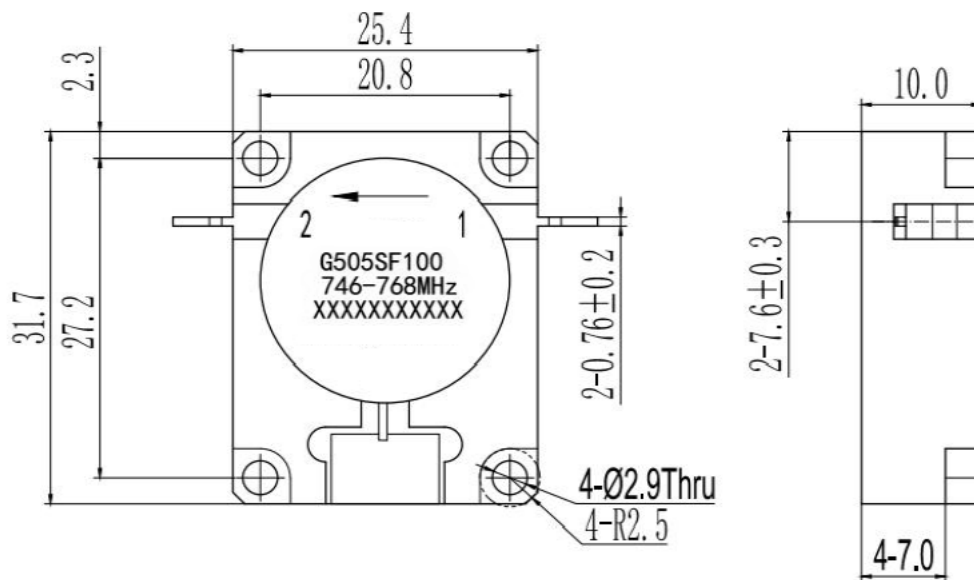
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G505A[840-925]MHz	0.840	0.925	0.883	0.085	23	0.3	1.15	150	
G505A[869-894]MHz	0.869	0.894	0.882	0.025	23	0.325	1.15	150	-65
G505A[925-960]MHz	0.925	0.960	0.943	0.035	25	0.25	1.15	100	
G505A[1800-1950]MHz	1.800	1.950	1.8750	0.150	22	0.3	1.17	150	
G505A[1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	150	
G505A[1920-1980]MHz	1.920	1.980	1.9500	0.060	25	0.2	1.15	100	
G505A[1930-1990]MHz	1.930	1.990	1.9600	0.060	25	0.2	1.15	100	
G505A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.15	100	

Drop-in Isolator G505S Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

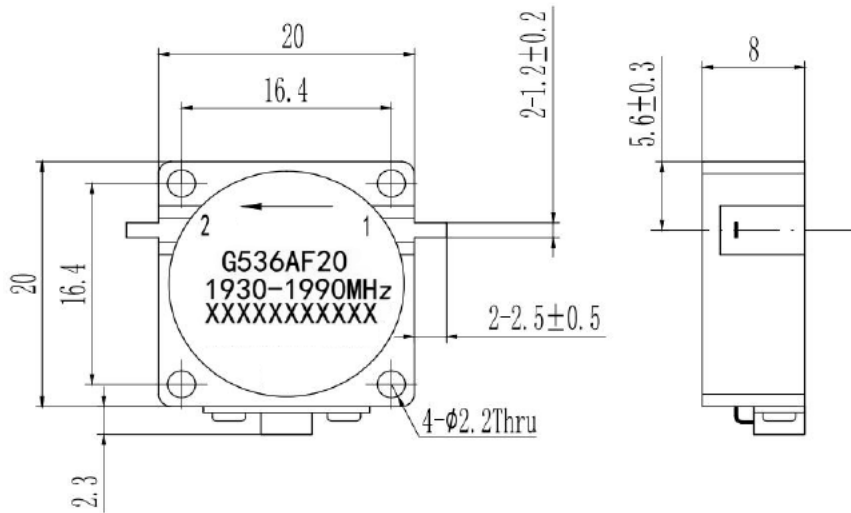
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G505S [729-746]MHz	0.729	0.746	0.738	0.017	25	0.25	1.12	100	-70
G505S [746-768]MHz	0.746	0.768	0.757	0.022	25	0.25	1.12	100	-70
G505S [758-803]MHz	0.758	0.803	0.781	0.045	25	0.25	1.12	100	-70
G505S [791-821]MHz	0.791	0.821	0.805	0.030	25	0.25	1.12	100	-70
G505S [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	100	-70
G505S [1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.12	100	-70
G505S [2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.25	1.12	100	-70

Drop-in Isolator G536A Series

1. Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2. Dimensions



3. Specifications

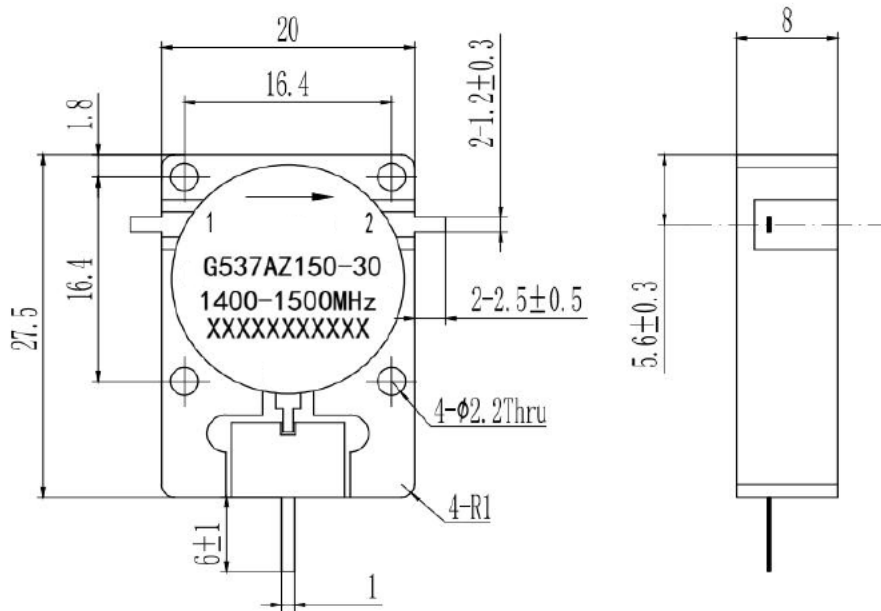
Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
G536A [820-835]MHz	0.820	0.835	0.828	0.015	23	0.3	1.15	150	
G536A [832-860]MHz	0.832	0.860	0.846	0.028	23	0.3	1.15	60	
G536A [840-845]MHz	0.840	0.845	0.843	0.005	23	0.3	1.15	60	
G536A [885-915]MHz	0.885	0.915	0.900	0.030	23	0.3	1.15	60	
G536A [869-894]MHz	0.869	0.894	0.8815	0.025	25	0.3	1.15	100	
G536A [920-925]MHz	0.920	0.925	0.9225	0.005	23	0.3	1.15	60	
G536A [1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.15	60	
G536A [1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	60	
G536A [1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.15	60	
G536A [1930-1990]MHz	1.930	1.990	1.9600	0.060	23	0.25	1.15	60	
G536A [2000-2500]MHz	2.000	2.500	2.2500	0.500	18	0.35	1.28	100	
G536A [2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.25	1.15	60	
G536A [2200-2300]MHz	2.200	2.300	2.2500	0.100	23	0.25	1.15	60	
G536A [2320-2370]MHz	2.320	2.370	2.3450	0.050	23	0.25	1.15	60	
G536A [2500-2570]MHz	2.500	2.570	2.5350	0.070	23	0.25	1.15	60	
G536A [2570-2690]MHz	2.570	2.690	2.6300	0.120	22	0.25	1.17	60	

Drop-in Isolator G537A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G537A[851-866]MHz	0.851	0.866	0.859	0.015	25	0.25	1.15	150	
G537A[865-880]MHz	0.865	0.880	0.873	0.015	23	0.3	1.15	150	
G537A[869-894]MHz	0.869	0.894	0.8815	0.025	23	0.3	1.15	150	
G537A[880-920]MHz	0.880	0.920	0.9000	0.040	23	0.3	1.15	150	
G537A[920-960]MHz	0.920	0.960	0.9400	0.040	23	0.3	1.15	100	
G537A[1452-1492]MHz	1.452	1.492	1.4720	0.040	25	0.25	1.15	100	
G537A[1710-1755]MHz	1.710	1.755	1.7325	0.045	25	0.25	1.15	150	
G537A[1805-1880]MHz	1.805	1.880	1.8375	0.075	23	0.25	1.15	100	
G537A[1805-1920]MHz	1.805	1.920	1.8625	0.115	22	0.25	1.17	100	
G537A[1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.15	150	
G537A[2010-2025]MHz	2.010	2.025	2.0175	0.015	23	0.25	1.15	100	
G537A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.15	150	
G537A[2400-2500]MHz	2.400	2.500	2.4500	0.100	23	0.25	1.15	100	
G537A[2620-2690]MHz	2.620	2.690	2.6550	0.070	23	0.25	1.15	150	

Drop-in Isolator

Features:

UMTS, LTE Band
 PCB Soldering Re-flow
 Compact Package Design for PCB Applications



ELECTRICAL CHARACTERISTICS:

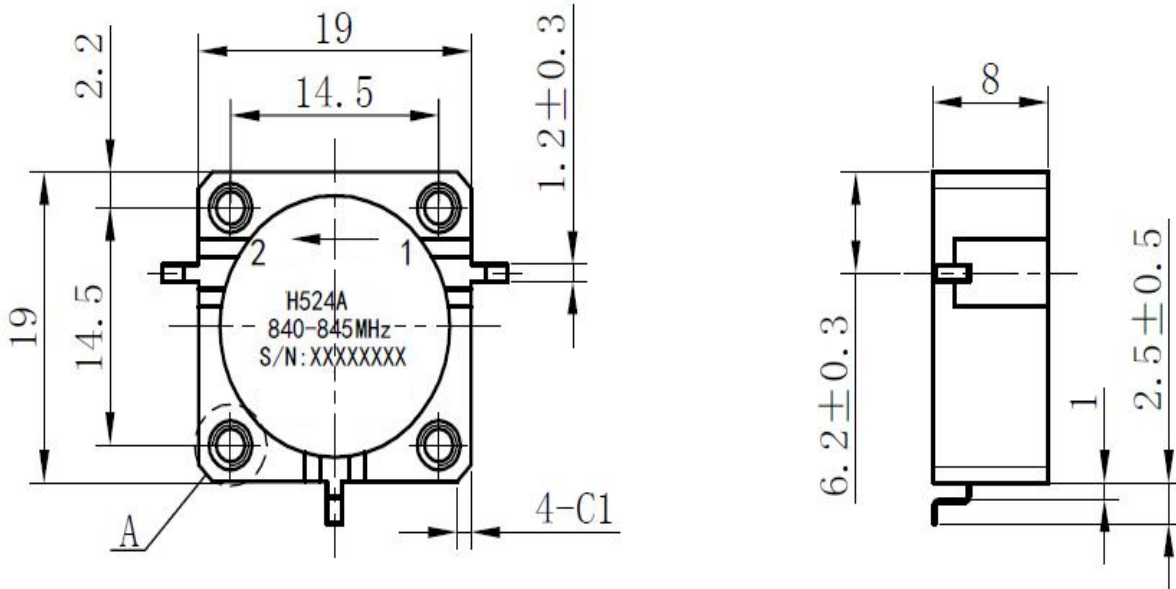
Model	Freq (GHz)	Bandwidth (MHz,max.)	Insertion Loss (dB,max.)	Isolation (dB,min.)	VSWR (dB,min.)	Forward Power (W,max)	Backward Power (W)	Temperature (°t)	Dimensions (mm)
G6060H	0.02-0.4	175	2	18	1.3	100	10-100	-20 - +70	60-60-25_5
G6466H	0.02-0.4	175	2	18	1.3	100	10-100	-10 - +60	s4-ss-22
G7070X	0.13-2	30	0.6	10	1.3	500	10-100	-20 - +70	10-10-15
G5050X	0.16-0.33	70	0.7	18	1.3	500	10-100	-30 - +70	50.0-50.0-14.8
G4545X	0.3-1.1	300	0.6	19	1.3	500	10-100	-30 - +70	45-45-13
G3538X	0.3-1.85	500	0.7	18	1.35	300	10-100	-30 - +70	35-30-11
G3546X	0.3-1.85	500	0.7	18	1.35	300	100	-30 - +70	35-45-11
G2525X	0.35-4	770	0.65	15	1.45	250	10-100	-30 - +70	25.4-25.4-1.0
G2532X	0.35-4	770	0.65	15	1.45	250	100	-30 - +70	25.4-31.r10
G5032X	0.45-2.7	400	0.8	38	1.25	250	10-100	-30 - +70	50.0-31.r1.0
G4020X	0.6-2.7	400	0.8	40	1.2	100	10-100	-30 - +70	40-20-0.s
G4027X	0.6-2.7	400	0.8	40	1.2	100	10-100	-30 - +70	40-27_5-0.s
G2027X	0.6-3.6	900	0.5	18	1.35	150	100	-30 - +70	20-27_5-0.s
G2020X	0.6-4	900	0.5	18	1.35	150	20	-30 - +70	20-20-0.s
G1919X	0.8-4.3	900	0.5	18	1.35	100	20	-30 - +70	19-19-0.6
G1925X	0.8-4.3	900	0.5	18	1.35	100	100	-30 - +70	19-19-0.s
G6466K	0.95-2	1050	0.65	16	1.4	100	10-100	0 - +60	64-6s-26
G5050A	1.5-3	1500	0.7	17	1.4	100	10-100	-10 - +60	50.s-49_5-19
G1313M	1.7-6	800	0.45	18	1.3	60	20	-30 - +70	12.7-12.7-7.2
G1313T	1.7-6	800	0.45	18	1.3	60	20	-30 - +70	12.r12.1-1.2
G3234A	2-4	2000	0.6	18	1.3	100	10-100	-10 - +60	32-34-21
G1626D	3.7-5	1000	0.5	18	1.3	100	10	-30 - +70	1s-2s-10.5
G2528C	3-6	3500	0.8	16	1.4	60	20	-10 - +60	25.4-20-14
G2123B	4-6	4000	0.6	18	1.35	60	20	0 - +60	21-22.5-15
G1220D	5-7	800	0.5	18	1.3	80	10	-30 - +70	12-20-9.5
G1623D	5-7	800	0.5	18	1.3	100	10	-30 - +70	1s-23-9_7
G0915D	7-18	6000	0.6	17	1.35	30	10	-30 - +70	0.9-15-1.0
G1622B	6-18	12000	1.5	11	1.9	30	10	0 - +60	1s-21.5-14

Drop-in Circulator H524A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

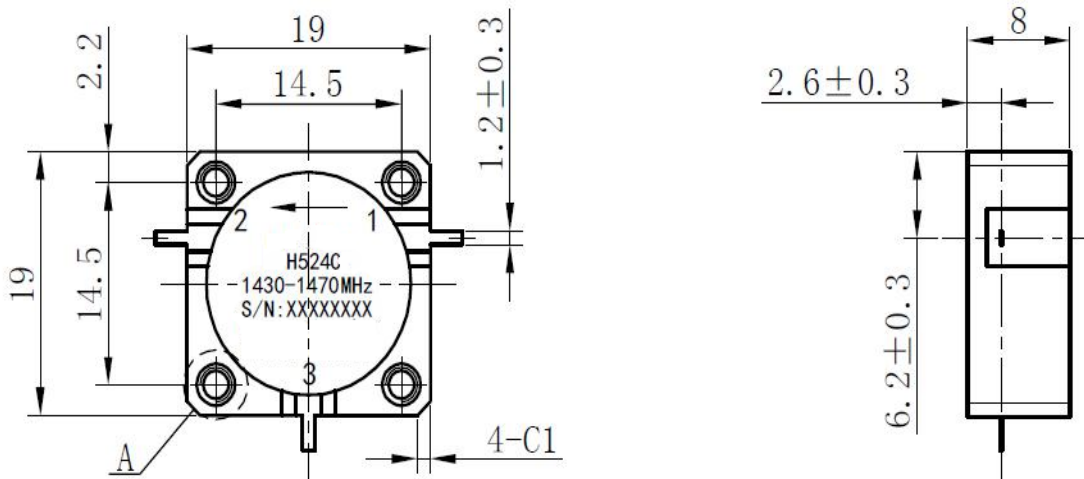
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H524A [840-845]MHz	0.840	0.845	0.8425	0.005	20	0.35	1.2	100	
H524A [902-928]MHz	0.902	0.928	0.9150	0.026	22	0.3	1.17	100	
H524A [930-960]MHz	0.930	0.960	0.9450	0.030	22	0.3	1.17	100	
H524A [1805-2170]MHz	1.805	2.170	1.8875	0.165	22	0.3	1.17	150	-65
H524A [1900-3000]MHz	1.900	3.000	2.450	1.100	20	0.35	1.2	100	-60

Drop-in Circulator H524C Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

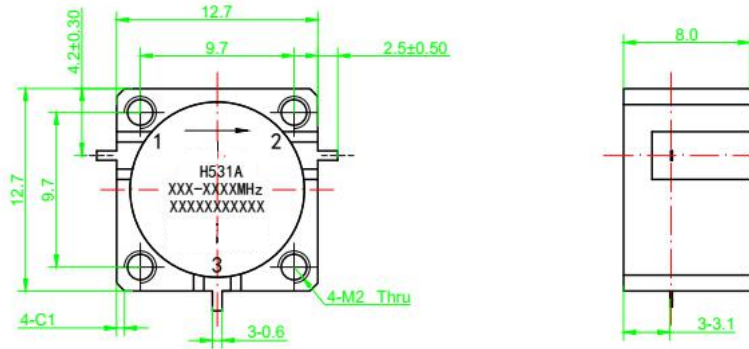
Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
H524C[1430-1470]MHz	1.430	1.470	1.4500	0.040	25	0.25	1.15	150	-70
H524C[1805-1920]MHz	1.805	1.920	1.8625	0.115	23	0.28	1.17	150	
H524C[1840-1920]MHz	1.840	1.920	1.8800	0.080	23	0.25	1.17	150	
H524C[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	150	
H524C[2300-2400]MHz	2.300	2.400	2.3500	0.100	23	0.25	1.17	150	
H524C[2300-2700]MHz	2.300	2.700	2.500	0.400	20	0.4	1.22	150	
H524C[2555-2655]MHz	2.555	2.655	2.605	0.100	23	0.25	1.17	100	
H524C[2500-2700]MHz	2.500	2.700	2.600	0.200	23	0.25	1.15	100	
H524C[3400-3800]MHz	3.400	3.800	3.600	0.400	23	0.25	2.3	100	
H524C[4100-4400]MHz	4.100	4.400	4.250	0.300	22	0.4	1.2	30	
H524C[4750-5100]MHz	4.750	5.100	4.925	0.350	22	0.35	1.2	10	

Drop-in Circulator H531A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

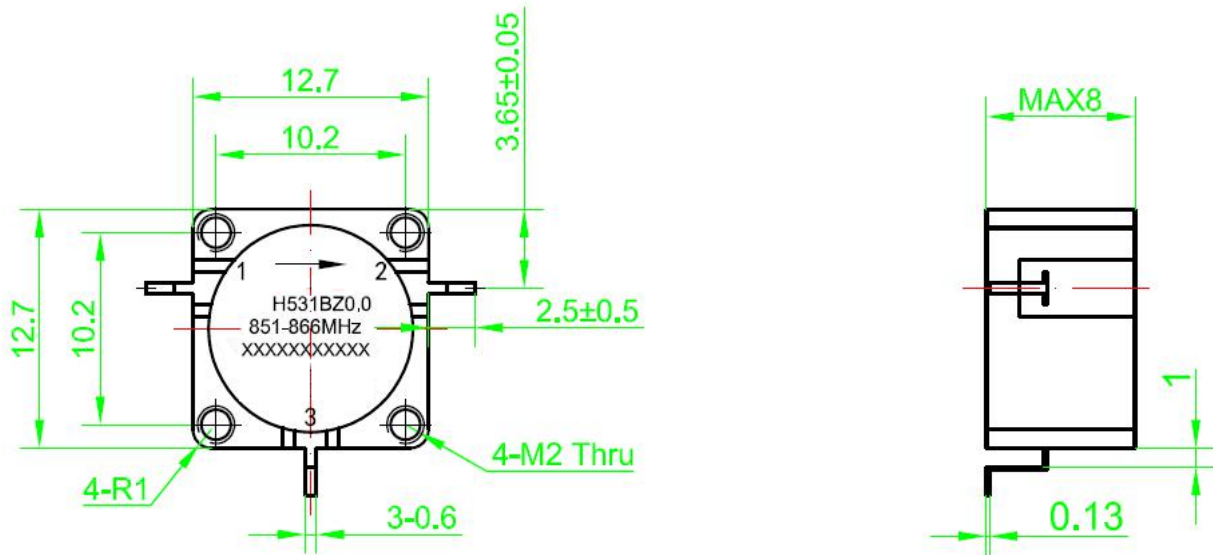
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531A[1805-1880]MHz	1.805	1.880	1.8425	0.075	22	0.35	1.17	100	
H531A[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531A[2000-2100]MHz	2.000	2.100	2.0500	0.100	20	0.35	1.22	75	
H531A[2110-2170]MHz	2.110	2.170	2.140	0.060	22	0.3	1.17	100	
H531A[2100-2200]MHz	2.100	2.200	2.150	0.100	20	0.35	1.22	75	
H531A[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	75	
H531A[2400-2550]MHz	2.400	2.550	2.475	0.150	23	0.3	1.15	75	
H531A[2500-2700]MHz	2.500	2.700	2.600	0.200	22	0.3	1.17	100	-75

Drop-in Circulator H531B Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

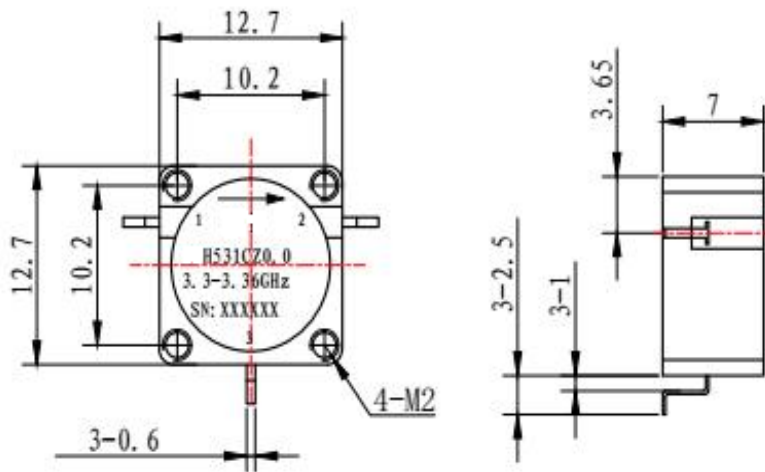
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531B[851-866]MHz	0.851	0.866	0.8585	0.015	21	0.45	1.2	50	
H531B[865-880]MHz	0.865	0.880	0.8725	0.015	21	0.45	1.2	50	
H531B[930-960]MHz	0.930	0.960	0.9450	0.030	21	0.45	1.2	50	
H531B[1880-1920]MHz	1.880	1.920	1.900	0.040	23	0.3	1.15	100	
H531B[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531B[1930-1995]MHz	1.930	1.995	1.963	0.065	23	0.3	1.15	100	
H531B[2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.3	1.15	100	
H531B[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	100	
H531B[2400-2500]MHz	2.400	2.500	2.450	0.100	23	0.3	1.15	100	
H531B[2550-2650]MHz	2.550	2.650	2.600	0.100	23	0.3	1.15	100	

Drop-in Circulator H531C Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

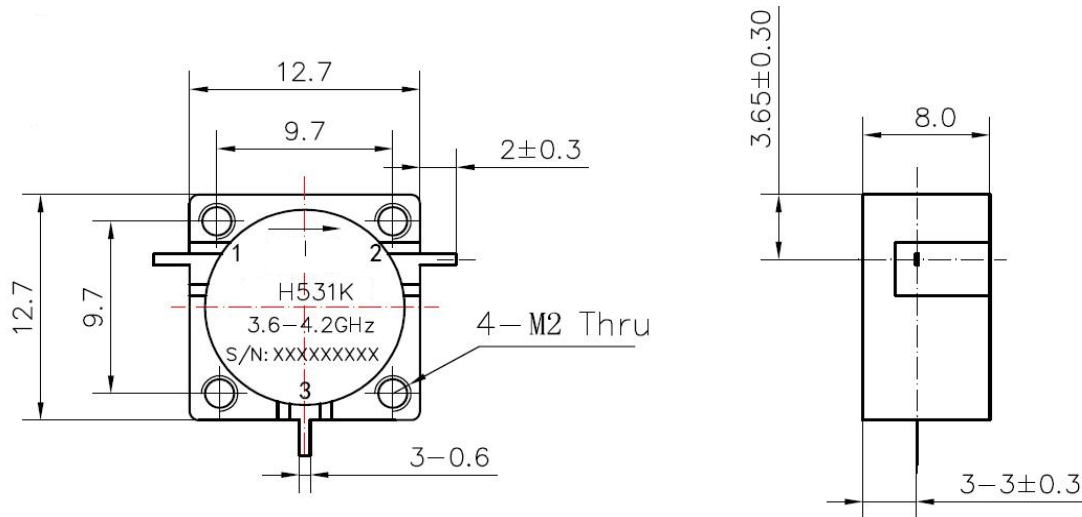
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531C[3.3-3.36]MHz	3.300	3.360	3.3300	0.060	22	0.3	1.17	100	
H531C[3400-3700]MHz	3.400	3.700	3.5500	0.300	21	0.4	1.2	50	
H531C[5790-5890]MHz	5.790	5.890	5.8500	0.100	23	0.3	1.17	20	

Drop-in Circulator H531K Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

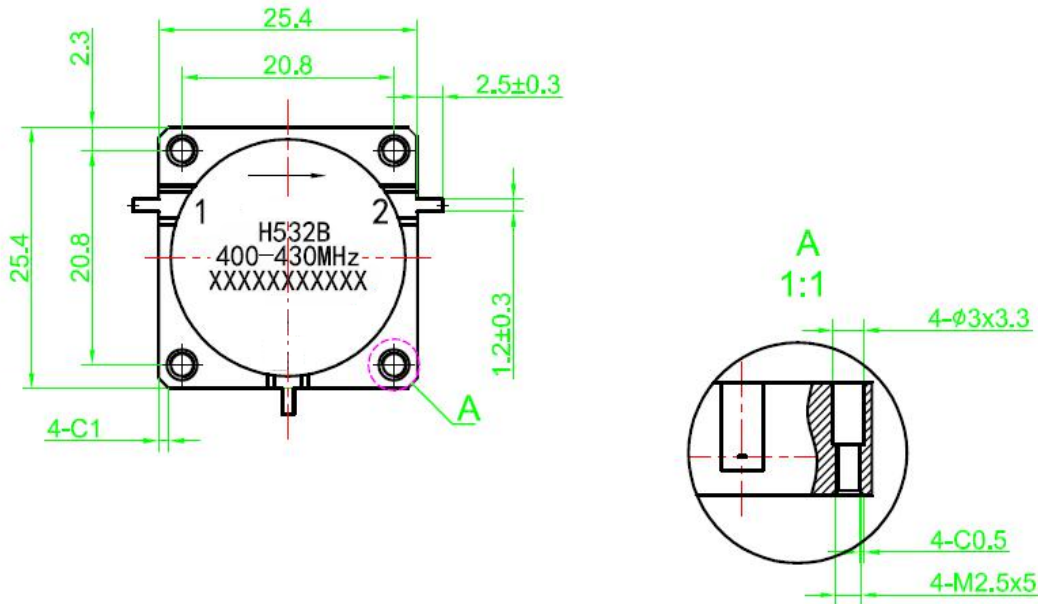
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531K[3.6-4.2]GHz	3.600	4.200	3.9000	0.600	20	0.35	1.25	50	
H531K[3.7-4.13]GHz	3.700	4.130	3.9150	0.430	20	0.35	1.25	50	
H531K[4.4-5]GHz	4.400	5.000	4.7000	0.600	20	0.35	1.25	50	
H531K[5.15-5.9]GHz	5.150	5.900	5.5250	0.750	20	0.35	1.25	50	
H531K[7.1-7.5]GHz	7.100	7.500	7.300	0.400	22	0.4	1.2	10	
H531K[9.2-9.8]GHz	9.200	9.800	9.500	0.600	21	0.4	1.2	60	
H531K[10.1-10.6]GHz	10.100	10.600	10.350	0.500	22	0.4	1.2	20	

Drop-in Circulator H532B Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

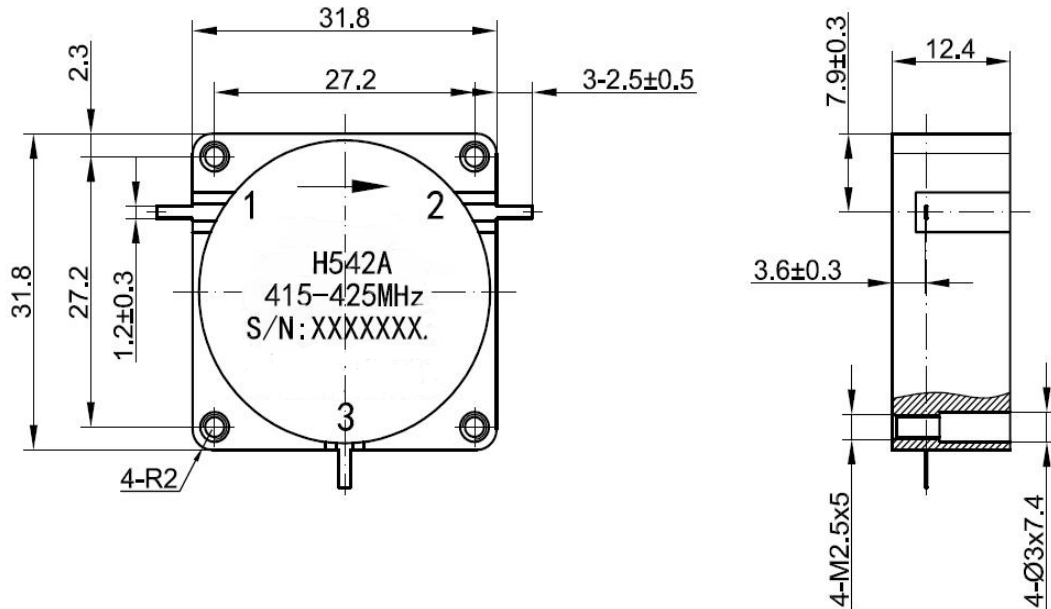
Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
H532B [400-430]MHz	0.400	0.430	0.4150	0.030	20	0.4	1.22	200	
H532B [566-600] MHz	0.566	0.600	0.5830	0.034	23	0.25	1.15	200	
H532B [566-678]MHz	0.566	0.678	0.6215	0.112	18	0.45	1.28	200	
H532B [600-684]MHz	0.600	0.684	0.6420	0.084	20	0.35	1.2	100	
H532B [600-700]MHz	0.600	0.700	0.6500	0.100	23	0.35	1.15	200	-65
H532B [700-740]MHz	0.700	0.740	0.7200	0.040	22	0.22	0.25	100	-70
H532B [758-803]MHz	0.758	0.803	0.7805	0.045	25	0.2	1.12	250	-70
H532B [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H532B [1805-1880]MHz	1.805	1.880	1.838	0.075	23	0.25	1.15	300	-75
H532B [1930-1995]MHz	1.930	1.995	1.963	0.075	23	0.25	1.15	300	-75
H532B [2110-2170]MHz	2.110	2.170	2.140	0.060	25	0.2	1.12	250	-75

Drop-in Circulator H542A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

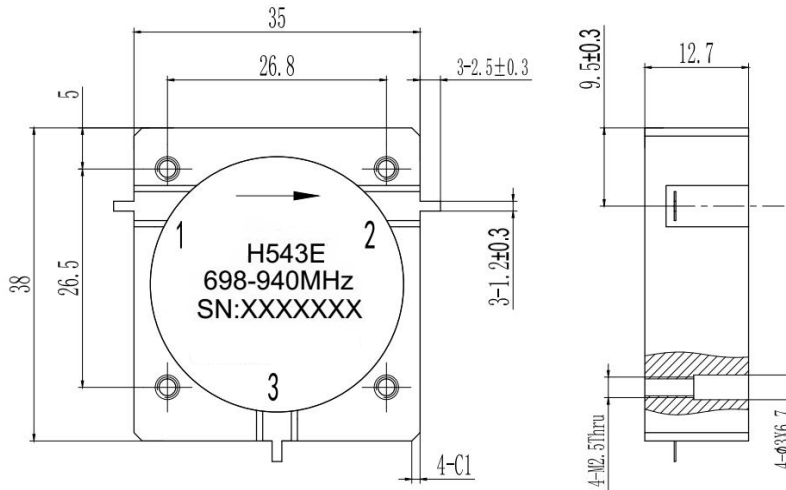
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H542A [415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	100	
H542A [470-510]MHz	0.470	0.510	0.4850	0.040	20	0.15	1.22	100	
H542A [560-680]MHz	0.560	0.680	0.6200	0.080	20	0.15	1.22	100	
H542A [700-960]MHz	0.700	0.960	0.8300	0.260	16	0.5	1.38	300	
H542A [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	400	-75
H542A [1217-1238]MHz	1.217	1.238	1.2275	0.021	23	0.25	1.15	300	
H542A [1565-1586]MHz	1.565	1.586	1.5755	0.021	23	0.25	1.15	300	
H542A [1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.15	400	-70
H542A [1800-2175]MHz	1.800	2.175	1.9875	0.375	22	0.3	1.17	300	
H542A [1805-1880]MHz	1.805	1.880	1.838	0.075	25	0.2	1.12	350	-75
H542A [2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.25	1.15	400	-75

Drop-in Circulator H543E Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

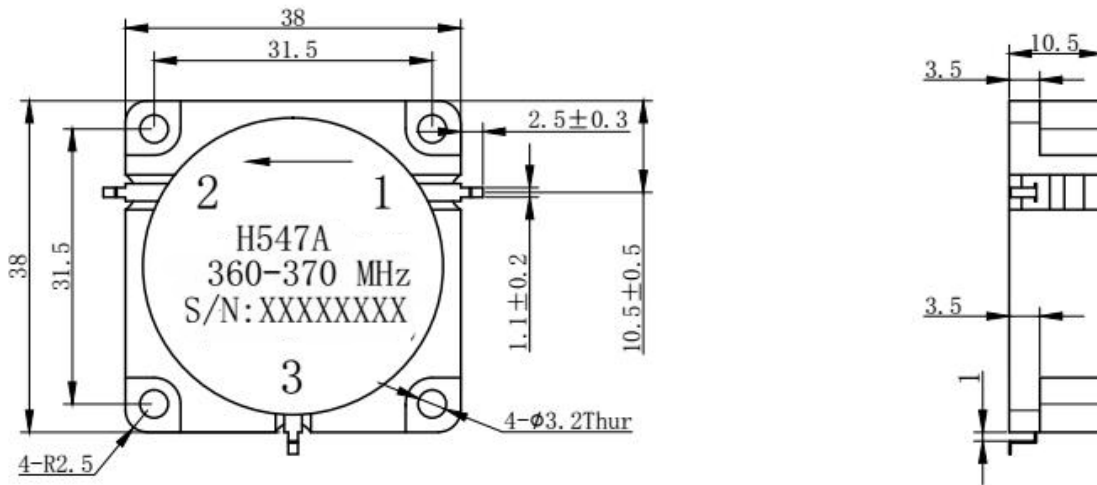
Part No.	Frequency (GHz)		Center Frequnc	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H543E [330-350]MHz	0.330	0.350	0.340	0.020	20	0.45	1.22	100	
H543E [400-430]MHz	0.400	0.430	0.4250	0.030	22	0.25	1.17	200	
H543E [470-570]MHz	0.470	0.570	0.5200	0.100	20	0.4	1.2	200	
H543E [500-650]MHz	0.500	0.650	0.5750	0.150	18	0.45	1.28	100	
H543E [698-940]MHz	0.698	0.940	0.8190	0.242	18	0.4	1.28	100	

Drop-in Circulator H547A Series

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



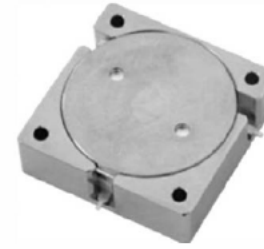
3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H547A0.0[360-370]MHz	0.360	0.370	0.365	0.010	23	0.25	1.15	150	
H547A0.0[395-435]MHz	0.385	0.435	0.4050	0.040	19	0.45	1.25	150	-60
H547A0.0[415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	200	
H547A0.0[470-520]MHz	0.470	0.520	0.4950	0.050	20	0.35	1.22	200	
H547A0.0[566-678]MHz	0.566	0.678	0.6220	0.112	20	0.45	1.22	150	-65

Drop-in Circulator

Features:

UMTS, LTE Band
 PCB Soldering Re-flow
 Compact Package Design for PCB Applications



ELECTRICAL CHARACTERISTICS:

Model	Freq (GHz)	Bandwidth (MHz,max.)	Insertion Loss (dB,max.)	Isolation (dB,min.)	VSWR (dB,min.)	Average Power (max)	Temperature (°C)	Dimensions (mm)
H6060H	0.02-0.4	175	2	18	13	100	-10 - +60	50-50-25.5
H6466H	0.02-0.4	175	2	18	13	100	-10 - +60	64*66*22
H5050X	0.15-0.33	70	0.7	18	13	400	-30 - +70	50.8*50.8*14.8
H4545X	0.5-1	300	0.5	18	13	400	-30 - +70	45-45-13
H3538X	0.3-1.85	500	0.7	18	1.35	300	-30 - +70	35-35-11
H3838X	0.3-1.85	106	0.4	20	1.25	300	-30 - +70	38*38*11
H2525X	0.35-4	770	0.65	15	1.45	250	-30 - +70	25.4*25.4*10
H2020X	0.6-4	900	0.5	18	1.35	100	-30 - +70	20*20*8.6
H1919X	0.8-4.3	900	0.5	18	1.35	100	-30 - +70	19-19*8.6
H6466K	0.95-2	1050	0.7	16	1.4	100	-10 - +60	64*66*26
H1313T	1.71-5.9	800	0.45	18	1.3	100	-30 - +70	12.7*12.7*7.2
H5050A	1.5-3	1500	0.7	17	1.4	100	0 - +60	50.8*49.5*19
H4040A	1.7-3	1200	0.7	16	1.35	200	0 - +60	40-40-20
H1313M	1.71-5.9	800	0.45	18	1.3	100	-30 - +70	12.7*12.7*7.2
H2525C	2.7-6	3500	0.8	16	1.4	200	-30 - +70	25.4*28*14
H3234A	2-4	2000	0.6	16	1.35	100	0 - +60	32*34*21
H1822D	4-5	1000	0.4	18	1.35	60	-30 - +70	18-22-10.4
H2123B	4-8	4000	0.6	18	1.35	60	0 - +60	21*22.5*15
H1220D	5-6.5	800	0.5	18	1.3	60	-30 - +70	12*20*9.5
H1623D	5-6.5	800	0.5	18	1.3	50	-30 - +70	16*23*9.7
H1319C	6-12	4000	0.5	18	1.3	50	0 - +60	13-19-12.7
H0915D	7-18	6000	0.6	17	1.35	30	-30 - +70	8.9*15*7.8